

# N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V} \,$

### **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

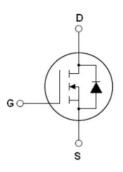
#### **Features**

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- ●Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

## **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

| V <sub>DS min@Tjmax</sub> | 550 | V  |
|---------------------------|-----|----|
| R <sub>DS(ON)TYP</sub> .  | 150 | mΩ |
| $I_D$                     | 17  | Α  |
| Qg                        | 22  | nC |



Schematic diagram

♦ Intrinsic fast-recovery body diode

# **Package Marking And Ordering Information**

| Device      | Device Package | Marking     |
|-------------|----------------|-------------|
| NCE50NF180D | TO-263-2L      | NCE50NF180D |



TO-263

Table 1. Absolute Maximum Ratings (T<sub>c</sub>=25℃)

| Parameter  | Symbol                  | Value   | Unit |
|--|-------------------------|---------|------|
| Drain-Source Voltage (Vgs=0V)  | V <sub>DS</sub>         | 500     | V    |
| Gate-Source Voltage (V <sub>DS=0</sub> V) ,AC (f>1 Hz)                   | Vgs                     | ±30     | V    |
| Gate-Source Voltage (V <sub>DS</sub> =0V) ,DC                            | Vgs                     | ±20     | V    |
| Continuous Drain Current at Tc=25°C                                      | I <sub>D (DC)</sub>     | 17      | Α    |
| Continuous Drain Current at Tc=100°C                                     | I <sub>D (DC)</sub>     | 11.9    | Α    |
| Pulsed drain current (Note 1)  | I <sub>DM (pluse)</sub> | 51      | А    |
| Maximum Power Dissipation(Tc=25℃)  | P₀                      | 129     | W    |
| Derate above 25°C  |                         | 0.86    | W/°C |
| Single pulse avalanche energy (Note 2)                                   | Eas                     | 62.5    | mJ   |
| Single pulse avalanche current (Note 2)                                  | I <sub>AS</sub>         | 5       | А    |
| Repetitive Avalanche energy $ ,   t_{AR}$ limited by $T_{jmax}$ (Note 1) | E <sub>AR</sub>         | 0.54    | mJ   |
| Reverse diode dv/dt, $V_{DS} \le 400 \text{ V,I}_{SD} < I_D$             | dv/dt                   | 15      | V/ns |
| Drain Source voltage slope,V <sub>DS</sub> ≤400 V                        | dv/dt                   | 50      | V/ns |
| Operating Junction and Storage Temperature Range                         | $T_{J}$ , $T_{STG}$     | -55+175 | °C   |



#### **Table 2. Thermal Characteristic**

| Parameter   | Symbol            | Value | Unit  |
|---|-------------------|-------|-------|
| Thermal Resistance, Junction-to-Case (Maximum)    | R <sub>thJC</sub> | 1.16  | °C /W |
| Thermal Resistance, Junction-to-Ambient (Maximum) | R <sub>thJA</sub> | 62    | °C /W |

Table 3. Electrical Characteristics (TA=25<sup>o</sup>Cunless otherwise noted)

| Parameter                                | Symbol              | Condition   | Min | Тур  | Max  | Unit |
|--|---------------------|---|-----|------|------|------|
| On/off states                            |                     |   |     |      |      |      |
| Drain-Source Breakdown Voltage           | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V I <sub>D</sub> =250uA                           | 500 |      |      | V    |
| Zero Gate Voltage Drain Current(Tc=25℃)  | I <sub>DSS</sub>    | V <sub>DS</sub> =500V,V <sub>GS</sub> =0V                           |     |      | 10   | μA   |
| Zero Gate Voltage Drain Current(Tc=125℃) | I <sub>DSS</sub>    | V <sub>DS</sub> =500V,V <sub>GS</sub> =0V                           |     |      | 300  | μA   |
| Gate-Body Leakage Current                | I <sub>GSS</sub>    | V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V                           |     |      | ±200 | nA   |
| Gate Threshold Voltage                   | $V_{GS(th)}$        | $V_{DS}=V_{GS},I_{D}=250uA$   | 3   |      | 5    | V    |
| Drain-Source On-State Resistance         | R <sub>DS(ON)</sub> | V <sub>GS</sub> =10V, I <sub>D</sub> =8.5A                          |     | 150  | 180  | mΩ   |
| Dynamic Characteristics                  |                     |   |     |      |      |      |
| Gate Resistance                          | Rg                  | F=1MHZ, D-S short   |     | 18   |      | Ω    |
| Input Capacitance                        | C <sub>lss</sub>    | ., 50,474 074   |     | 1157 |      | pF   |
| Output Capacitance                       | Coss                | $V_{DS}=50V, V_{GS}=0V,$  |     | 52   |      | pF   |
| Reverse Transfer Capacitance             | C <sub>rss</sub>    | F=1MHz  |     | 4.8  |      | pF   |
| Total Gate Charge                        | Qg                  |   |     | 22   |      | nC   |
| Gate-Source Charge                       | Q <sub>gs</sub>     | V <sub>DS</sub> =400V,I <sub>D</sub> =8.5A,<br>V <sub>GS</sub> =10V |     | 9.1  |      | nC   |
| Gate-Drain Charge                        | $Q_{gd}$            |   |     | 5.1  |      | nC   |
| Gate plateau voltage                     | Vgp                 |   |     | 6.6  |      | V    |
| Switching times                          |                     |   |     |      |      |      |
| Turn-on Delay Time                       | t <sub>d(on)</sub>  |   |     | 12   |      | nS   |
| Turn-on Rise Time                        | tr                  | $V_{DD}$ =400 $V$ , $I_{D}$ =8.5 $A$ ,                              |     | 10   |      | nS   |
| Turn-Off Delay Time                      | t <sub>d(off)</sub> | $R_G$ =4 $\Omega$ , $V_{GS}$ =10 $V$                                |     | 56   |      | nS   |
| Turn-Off Fall Time                       | t <sub>f</sub>      |   |     | 8    |      | nS   |
| Source- Drain Diode Characteristics      |                     |   |     |      |      |      |
| Source-drain current(Body Diode)         | I <sub>SD</sub>     | T 05°0  |     |      | 17   | Α    |
| Pulsed-Source-drain current(Body Diode)  | I <sub>SDM</sub>    | T <sub>C</sub> =25°C  |     |      | 51   | Α    |
| Forward on voltage                       | V <sub>SD</sub>     | Tj=25°C,I <sub>SD</sub> =17A,V <sub>GS</sub> =0V                    |     | 0.9  | 1.1  | V    |
| Reverse Recovery Time                    | t <sub>rr</sub>     |   |     | 165  |      | nS   |
| Reverse Recovery Charge                  | Q <sub>rr</sub>     | Tj=25°C,I <sub>F</sub> 8.5A,  |     | 0.83 |      | uC   |
| Peak reverse recovery current            | I <sub>rrm</sub>    | di/dt=100A/µs   |     | 10   |      | Α    |

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25  $^{\circ}$ C,VDD=50V,VG=10V, R<sub>G</sub>=25 $\Omega$ 



# TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

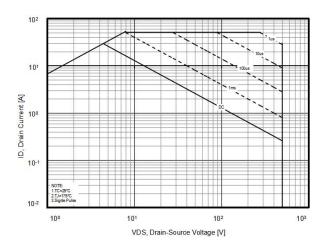


Figure 3. Output characteristics

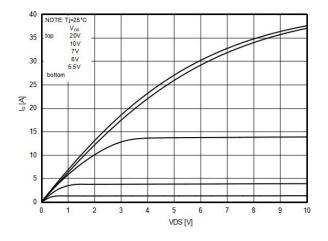


Figure 5. Static drain-source on resistance

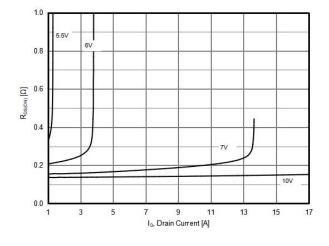


Figure 2. Source-Drain Diode Forward Voltage

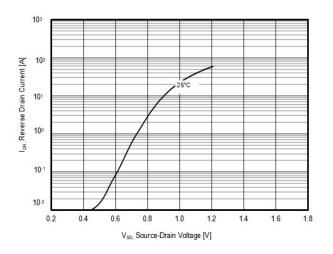


Figure 4. Transfer characteristics

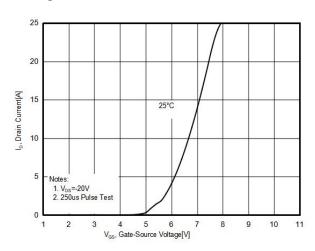


Figure 6. R<sub>DS(ON)</sub> vs Junction Temperature

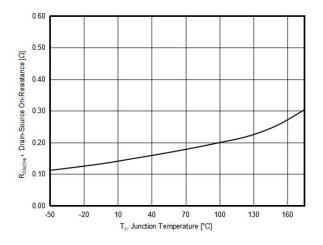




Figure 7. BV<sub>DSS</sub> vs Junction Temperature

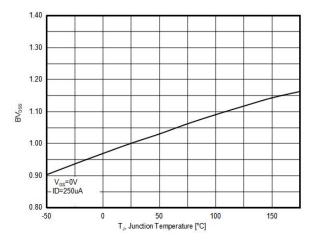


Figure 9. Gate charge waveforms

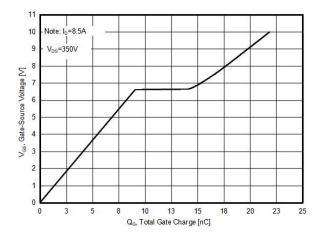


Figure 8. Maximum ID vs Junction Temperature

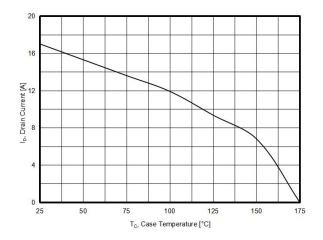
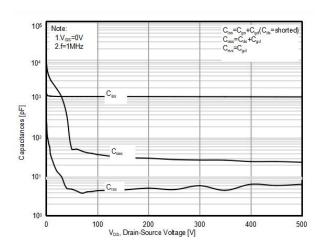


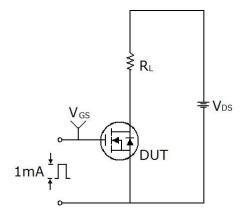
Figure 10. Capacitance

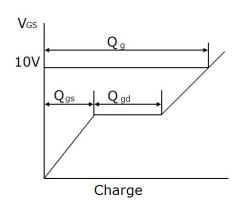




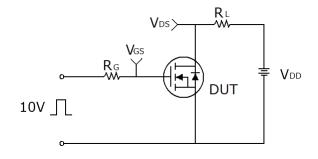
# **Test circuit**

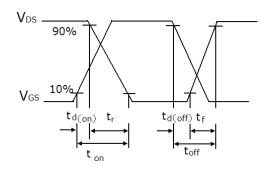
# 1) Gate charge test circuit & Waveform



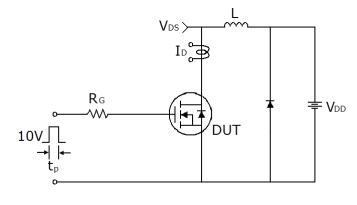


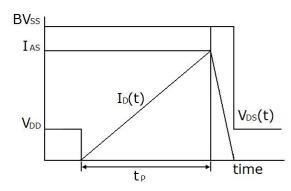
# 2) Switch Time Test Circuit:





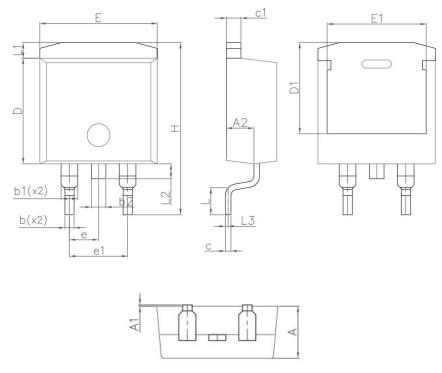
# 3) Unclamped Inductive Switching Test Circuit & Waveforms







# **TO-263-E Package Information**



| Symbol | Dimensions | In Millimeters | Dimensions In Inches |          |  |  |
|--------|------------|----------------|----------------------|----------|--|--|
|        | Min.       | Max.           | Min.                 | Max.     |  |  |
| А      | 4.20       | 4.60           | 0.165                | 0.181    |  |  |
| A1     | 0.00       | 0.25           | 0.00                 | 0.010    |  |  |
| A2     | 2.20       | 2.60           | 0.087                | 0.102    |  |  |
| b      | 0.70       | 0.90           | 0.028                | 0.035    |  |  |
| b1     | 1.20       | 1.75           | 0.047                | 0.069    |  |  |
| b2     | 1.17       | 1.37           | 0.046                | 0.054    |  |  |
| С      | 0.40       | 0.60           | 0.016                | 0.024    |  |  |
| c1     | 1.15       | 1.40           | 0.045                | 0.055    |  |  |
| D      | 9.10       | 9.30           | 0.358                | 0.366    |  |  |
| D1     | 7.63       | 8.23           | 0.300                | 0.324    |  |  |
| E      | 10.05      | 10.45          | 0.396                | 0.411    |  |  |
| E1     | 8.35       | 8.95           | 0.329                | 0.352    |  |  |
| е      | 2.54       | 2.54BSC        |                      | 0.100BSC |  |  |
| e1     | 5.08BSC    |                | 0.200BSC             |          |  |  |
| Н      | 14.61      | 15.88          | 0.575                | 0.625    |  |  |
| L      | 1.78       | 2.79           | 0.070                | 0.110    |  |  |
| L1     | 1.36       | 1.36REF        |                      | IREF     |  |  |
| L2     | 1.30       | 1.30REF        |                      | 0.051REF |  |  |



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